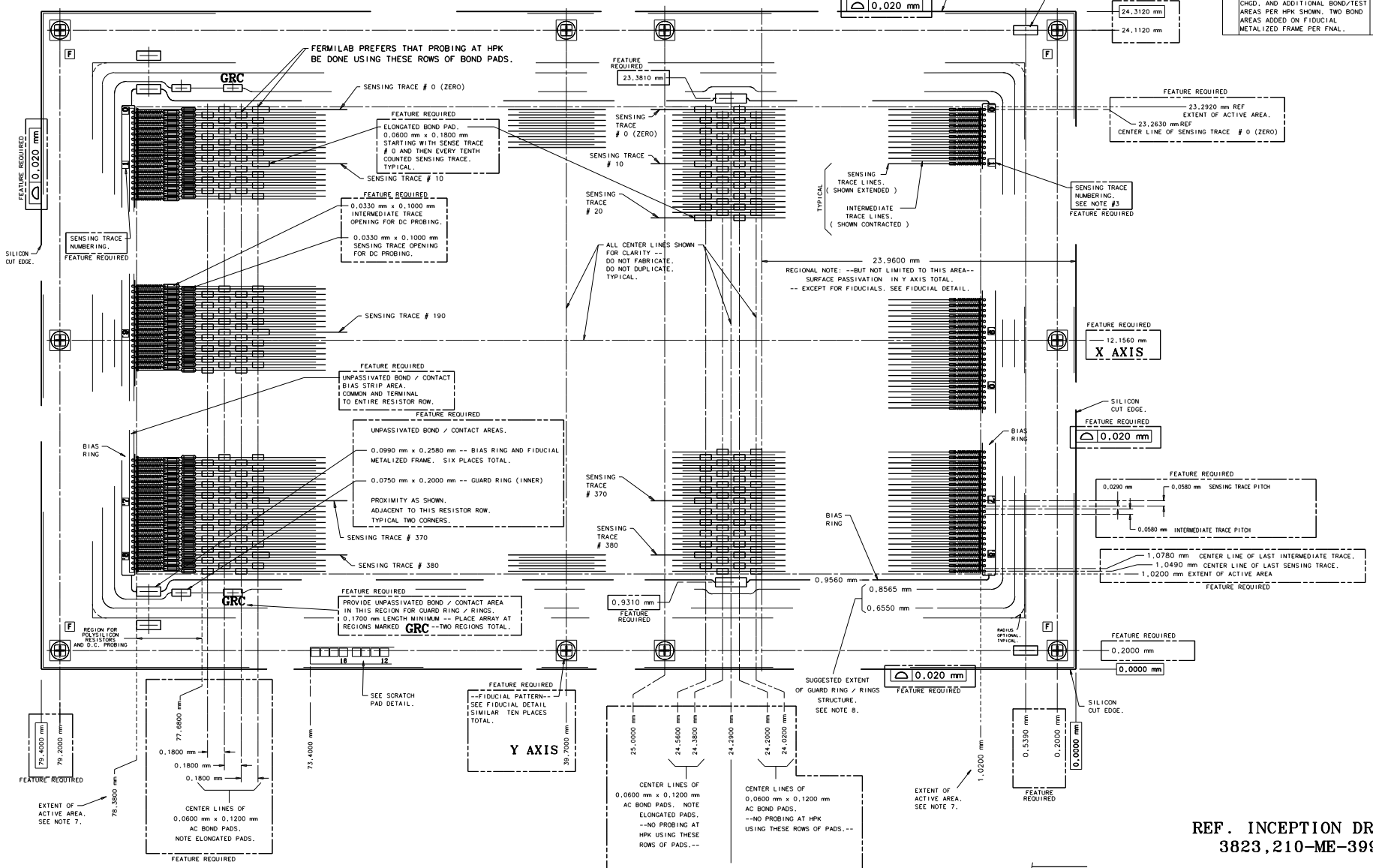
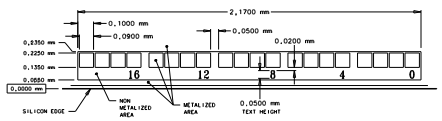
REV	DESCRIPTION	DRAWN / APPROVED	DATE / DATE
A	SENSING TRACE NUMBERING SCHEME REVISED. ELONGATED AC BOND PAD POSITIONS REDEFINED AND NOTED. FIDUCIAL DESIGN CHGD. AND ADDITIONAL BOND/TEST AREAS PER HPK SHOWN. TWO BOND AREAS ADDED ON FIDUCIAL METALIZED FRAME PER FNAL.	J. KOWALSKI	12 JUNE, 2002

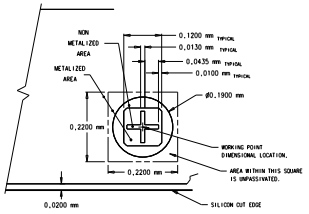


REF. INCEPTION DRAWING: 3823.210-ME-399381

1. ALL MASK FEATURES TO BE INTERPRETED AS BEING REFERENCED TO THE X - Y AXES.
2. NECESSARY / REQUIRED FEATURES AND DIMENSIONS ARE SHOWN WITHIN A BORDERED AREA ——————— WITH ADJACENT NOTATION : " FEATURE REQUIRED ". OTHER FEATURES MAY BE CHANGED SUBJECT TO FERMILAB REVIEW.
3. SUGGESTED SENSING TRACE NUMBERING SCHEME: CONSISTS OF ARABIC NUMERALS EVERY TENTH SENSING TRACE WITH THE NUMERAL INDICATING THE TENTHS DIGIT. DOTS / SQUARES ARE USED TO INDICATE THE HUNDREDTHS DIGIT.
4. ALL TRACE LINES SHOWN INDICATE THE CENTER OF THE STRIPS.
5. UNPASSIVATED BOND / CONTACT / BOND PAD AREAS ARE DESCRIBED AND REQUIRED AND ARE SUBJECT TO FERMILAB REVIEW.
6. THE SILICON CUT DIMENSIONS ARE FIXED AND REQUIRED.
7. THE EXPECTED ACTIVE LENGTH, ACTIVE AND CUT WIDTH AND DISTANCE FROM CUT END TO A.C. BOND PADS ARE BASED UPON HPK'S RECOMMENDATIONS. CHANGES ARE SUBJECT TO FERMILAB REVIEW.
8. VENDOR IS RESPONSIBLE FOR DETERMINING GUARD RING AND BIAS RING STRUCTURE DESIGNS. BUT THEY ARE SUBJECT TO FERMILAB REVIEW.
9. FIDUCIAL DESIGN / DETAILS MAY BE CHANGED. BUT THEY ARE SUBJECT TO FERMILAB REVIEW.



SCRATCH PAD DETAIL



FIDUCIAL DETAIL

ORIGINATOR	W.E.COOPER	04-APR-2002
DRAWN	J.KOWALSKI	10-APR-2003
CHECKED	R.DIMINA/F.LEINER	12-APR-2002
APPROVED	W.E.COOPER	12-APR-2002
USED ON		
MATERIAL		

FERMI NATIONAL ACCELERATOR LABORATORY
UNITED STATES DEPARTMENT OF ENERGY

D-ZERO RUN 2B
HPK SENSOR, LAYER 1 - 384 TRACES

SCALE	DRAWING NUMBER	SHEET	REV
NONE	3823.210-ME-399436	1 OF 1	A

CREATED WITH : Ideas9m3 GROUP: PPD/MECHANICAL DEPARTMENT